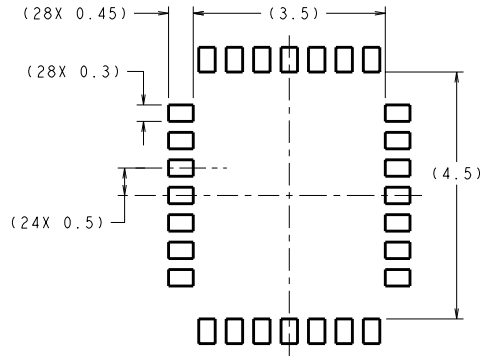
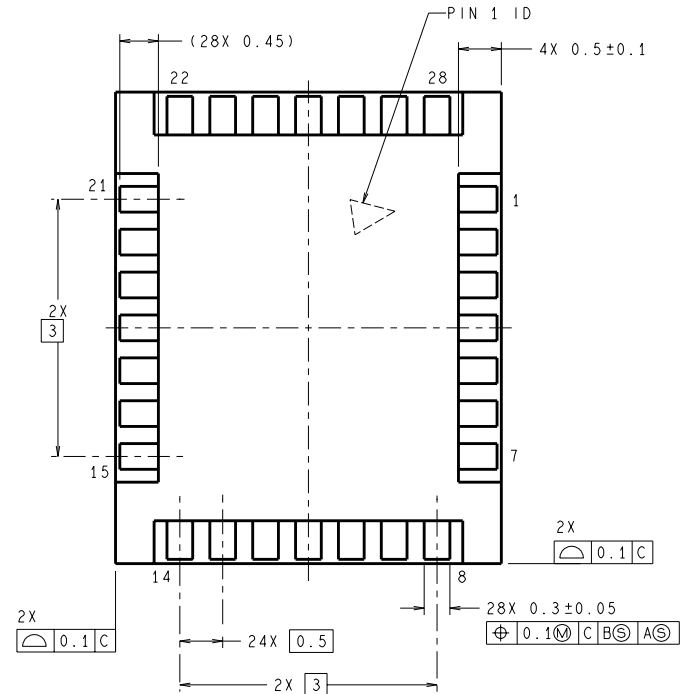
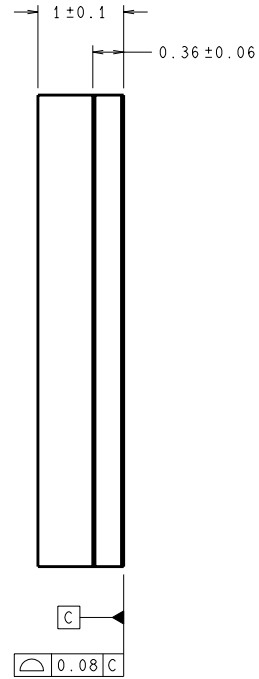
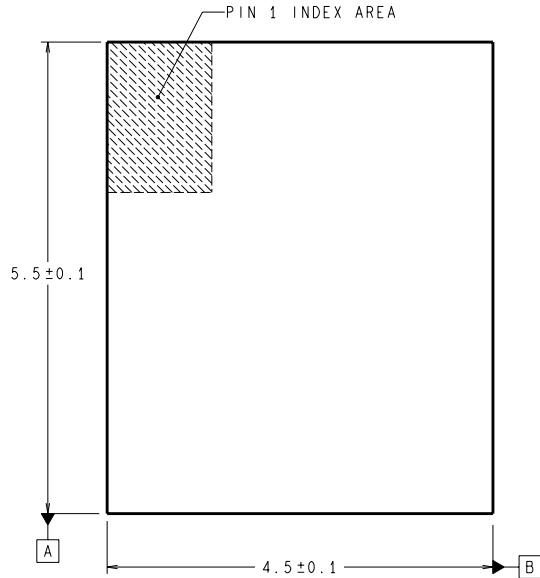


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12029	06/18/1998	TL/KH
B	UPDATE BOT METAL MASK LAYERS PER P/P DWG; REV NOTES 2 & 3; REV GEOMETRIC TOL	12097	09/24/1998	TL/



**RECOMMENDED LAND PATTERN**  
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
2. PLATING: Cu 15 TO 20 MICROMETERS  
Ni 10 ± 5 MICROMETERS  
Au 1 ± 0.5 MICROMETER
3. REFERENCE JEDEC REGISTRATION MO-208, VARIATION GEE, DATED SEPTEMBER 1998.

APPROVALS	DATE	 2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DRAWN T. LEQUANG	06/18/1998				
DTG. CHK.		<b>CSP, PLASTIC, LAMINATED,</b> <b>4.5 x 5.5 x 1.0 mm BODY,</b> <b>28 L, 0.5 mm PITCH</b>			
ENGR. CHK.					
 PROJECTION INCH MM		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-SLB28A	REV B
		DO NOT SCALE DRAWING		SHEET 1 of 1	